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CHARPIN-NICOLLE et al.

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(71) Applicant: **COMMISSARIAT A L'ENERGIE
ATOMIQUE ET AUX ENERGIES
ALTERNATIVES**, Paris (FR)

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(72) Inventors: **Christelle CHARPIN-NICOLLE**,
Grenoble Cedex 09 (FR); **Serge**
BLONKOWSKI, Grenoble Cedex 09
(FR); **Rémy GASSILLOUD**, Grenoble
Cedex 09 (FR); **Thomas MAGIS**,
Grenoble Cedex 09 (FR)

(73) Assignee: **COMMISSARIAT A L'ENERGIE
ATOMIQUE ET AUX ENERGIES
ALTERNATIVES**, Paris (FR)

(57) **ABSTRACT**

A resistive memory device including at least one first electrode based on a first metal and a second electrode based on a second metal, and a memory element in the form of a metal filament based on a third metal and inserted between the first and second electrodes, the memory element having a filament cross-section strictly smaller than the electrode cross-sections, wherein the third metal has a chemical composition, different from those of the first and second metals giving it an etching speed greater than those of the first and second metals, preferably such that the selectivity at the etching is greater than or equal to 3:1, vis-à-vis the first and second metals. A method for manufacturing such a device is also disclosed.

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